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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

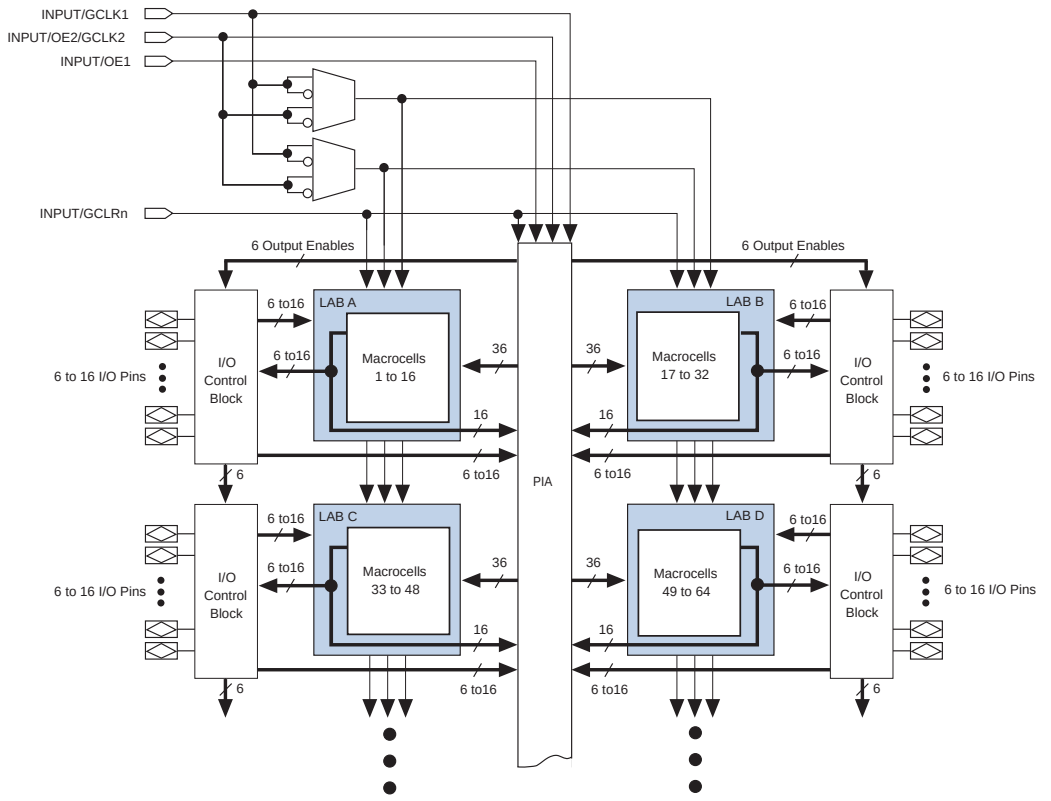
Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	10
Number of Macrocells	160
Number of Gates	3200
Number of I/O	64
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7160elc84-10

Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram



Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

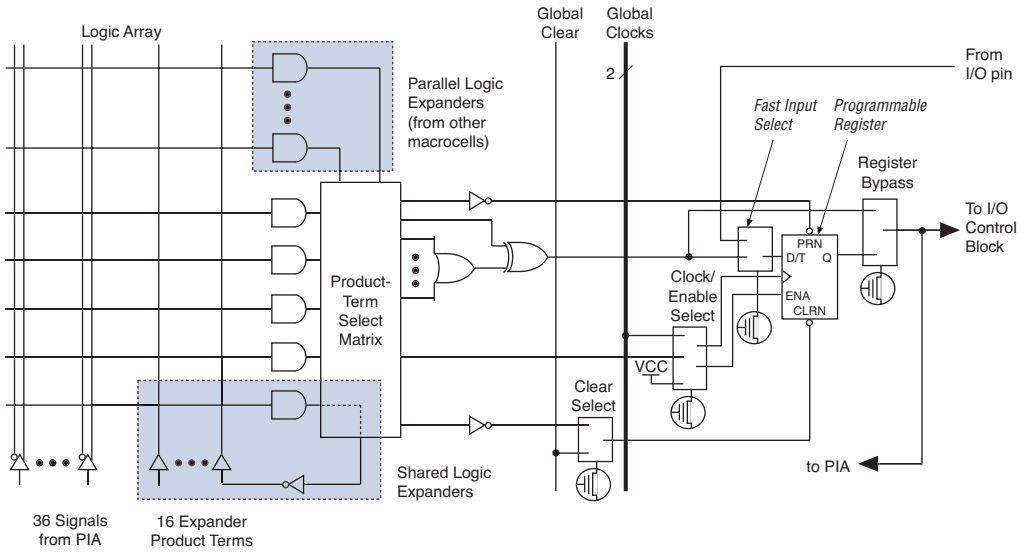
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-to-output performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, `GCLK1`, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, `GCLK1` or `GCLK2`.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (`GCLRn`). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms (“expanders”) that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

For more information on using the Jam language, refer to *AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor*.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the `TDI` input pin. Data is shifted out through the `TDO` output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.

2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.

3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.

4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.

5. *Verify*. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.

6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo Bit™ option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, and t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of `VCC` pins for internal operation and input buffers (`VCCINT`), and another set for I/O output drivers (`VCCIO`).

The `VCCINT` pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The `VCCIO` pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the `VCCIO` pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1}.

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-`OR` plane.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 9 describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (**http://www.altera.com**) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 9. MAX 7000 JTAG Instructions

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the `TDI` and `TDO` pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between `TDI` and `TDO`, allowing the IDCODE to be serially shifted out of `TDO`.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (**.jam**), Jam Byte-Code file (**.jbc**), or Serial Vector Format file (**.svf**) via an embedded processor or test equipment.

Figure 13. Switching Waveforms

t_R & t_F < 3 ns.
Inputs are driven at 3 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.

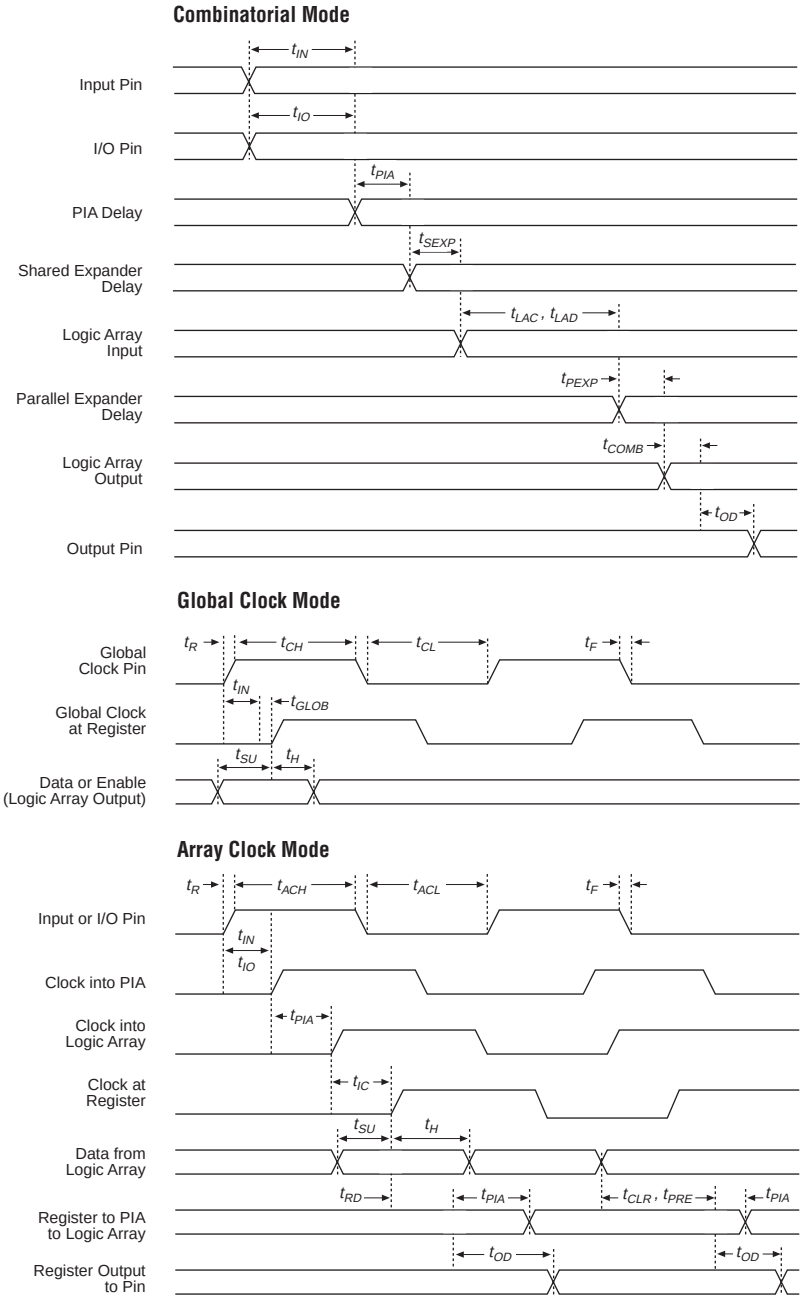


Table 20. MAX 7000 & MAX 7000E Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade -6		Speed Grade -7		Unit
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.4		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t_{FIN}	Fast input delay	*(2)*		0.8		1.0	ns
t_{SEXP}	Shared expander delay			3.5		4.0	ns
t_{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			2.0		3.0	ns
t_{LAC}	Logic control array delay			2.0		3.0	ns
t_{IOE}	Internal output enable delay	*(2)*				2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		2.0		2.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		2.5		2.5	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on, V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		7.0		7.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		4.5		4.5	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t_{SU}	Register setup time		3.0		3.0		ns
t_{H}	Register hold time		1.5		2.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	2.5		3.0		ns
t_{FH}	Register hold time of fast input	*(2)*	0.5		0.5		ns
t_{RD}	Register delay			0.8		1.0	ns
t_{COMB}	Combinatorial delay			0.8		1.0	ns
t_{IC}	Array clock delay			2.5		3.0	ns
t_{EN}	Register enable time			2.0		3.0	ns
t_{GLOB}	Global control delay			0.8		1.0	ns
t_{PRE}	Register preset time			2.0		2.0	ns
t_{CLR}	Register clear time			2.0		2.0	ns
t_{PIA}	PIA delay			0.8		1.0	ns
t_{LPA}	Low-power adder	*(8)*		10.0		10.0	ns

Table 21. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-10P)		MAX 7000 (-10) MAX 7000E (-10)		
			Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t_{SU}	Global clock setup time		7.0		8.0		ns
t_{H}	Global clock hold time		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	*(2)*	3.0		3.0		ns
t_{FH}	Global clock hold time of fast input	*(2)*	0.5		0.5		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns
t_{CH}	Global clock high time		4.0		4.0		ns
t_{CL}	Global clock low time		4.0		4.0		ns
t_{ASU}	Array clock setup time		2.0		3.0		ns
t_{AH}	Array clock hold time		3.0		3.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns
t_{ACH}	Array clock high time		4.0		4.0		ns
t_{ACL}	Array clock low time		4.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(3)*	4.0		4.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(4)*	1.0		1.0		ns
t_{CNT}	Minimum global clock period			10.0		10.0	ns
f_{CNT}	Maximum internal global clock frequency	*(5)*	100.0		100.0		MHz
t_{ACNT}	Minimum array clock period			10.0		10.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(5)*	100.0		100.0		MHz
f_{MAX}	Maximum clock frequency	*(6)*	125.0		125.0		MHz

Table 22. MAX 7000 & MAX 7000E Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-10P)		MAX 7000 (-10) MAX 7000E (-10)		
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.5		1.0	ns
t_{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t_{FIN}	Fast input delay	*(2)*		1.0		1.0	ns
t_{SEXP}	Shared expander delay			5.0		5.0	ns
t_{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			5.0		5.0	ns
t_{LAC}	Logic control array delay			5.0		5.0	ns
t_{IOE}	Internal output enable delay	*(2)*		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		2.0		2.5	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		5.5		6.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		5.5		5.5	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t_{SU}	Register setup time		2.0		3.0		ns
t_{H}	Register hold time		3.0		3.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	3.0		3.0		ns
t_{FH}	Register hold time of fast input	*(2)*	0.5		0.5		ns
t_{RD}	Register delay			2.0		1.0	ns
t_{COMB}	Combinatorial delay			2.0		1.0	ns
t_{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			5.0		5.0	ns
t_{GLOB}	Global control delay			1.0		1.0	ns
t_{PRE}	Register preset time			3.0		3.0	ns
t_{CLR}	Register clear time			3.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t_{LPA}	Low-power adder	*(8)*		11.0		11.0	ns

Table 25. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t_{SU}	Global clock setup time		11.0		11.0		12.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	*(2)*	3.0		–		5.0		ns
t_{FH}	Global clock hold time of fast input	*(2)*	0.0		–		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t_{CH}	Global clock high time		5.0		6.0		6.0		ns
t_{CL}	Global clock low time		5.0		6.0		6.0		ns
t_{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t_{AH}	Array clock hold time		4.0		4.0		5.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t_{ACH}	Array clock high time		6.0		6.5		8.0		ns
t_{ACL}	Array clock low time		6.0		6.5		8.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(3)*	6.0		6.5		8.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(4)*	1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
f_{CNT}	Maximum internal global clock frequency	*(5)*	76.9		76.9		62.5		MHz
t_{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(5)*	76.9		76.9		62.5		MHz
f_{MAX}	Maximum clock frequency	*(6)*	100		83.3		83.3		MHz

Table 30. EPM7064S Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
t_{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
t_{RD}	Register delay			1.2		1.6		1.0		2.0	ns
t_{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns
t_{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns
t_{EN}	Register enable time			2.6		3.2		3.0		5.0	ns
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns
t_{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns
t_{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns
t_{PIA}	PIA delay	*(7)*		1.1		1.3		1.0		1.0	ns
t_{LPA}	Low-power adder	*(8)*		12.0		11.0		10.0		11.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The $\mathbf{f_{MAX}}$ values represent the highest frequency for pipelined data.

(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t_{PIA}	PIA delay	*(7)*		1.6		2.0		1.0		2.0	ns
t_{LPA}	Low-power adder	*(8)*		11.0		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
(5) The $\mathbf{f_{MAX}}$ values represent the highest frequency for pipelined data.
(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.
(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$\mathbf{t_{PD1}}$	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
$\mathbf{t_{PD2}}$	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
$\mathbf{t_{SU}}$	Global clock setup time		4.1		7.0		11.0		ns
$\mathbf{t_{H}}$	Global clock hold time		0.0		0.0		0.0		ns
$\mathbf{t_{FSU}}$	Global clock setup time of fast input		3.0		3.0		3.0		ns
$\mathbf{t_{FH}}$	Global clock hold time of fast input		0.0		0.5		0.0		ns
$\mathbf{t_{CO1}}$	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
$\mathbf{t_{CH}}$	Global clock high time		3.0		4.0		5.0		ns
$\mathbf{t_{CL}}$	Global clock low time		3.0		4.0		5.0		ns
$\mathbf{t_{ASU}}$	Array clock setup time		1.0		2.0		4.0		ns

Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_H	Register hold time		1.7		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		2.3		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.7		0.5		1.0		ns
t_{RD}	Register delay			1.4		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.2		2.0		1.0	ns
t_{IC}	Array clock delay			3.2		5.0		6.0	ns
t_{EN}	Register enable time			3.1		5.0		6.0	ns
t_{GLOB}	Global control delay			2.5		1.0		1.0	ns
t_{PRE}	Register preset time			2.7		3.0		4.0	ns
t_{CLR}	Register clear time			2.7		3.0		4.0	ns
t_{PIA}	PIA delay	*(7)*		2.4		1.0		2.0	ns
t_{LPA}	Low-power adder	*(8)*		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The $\mathbf{f_{MAX}}$ values represent the highest frequency for pipelined data.

(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 37 and 38 show the EPM7256S AC operating conditions.

Table 37. EPM7256S External Timing Parameters *Note (1)*

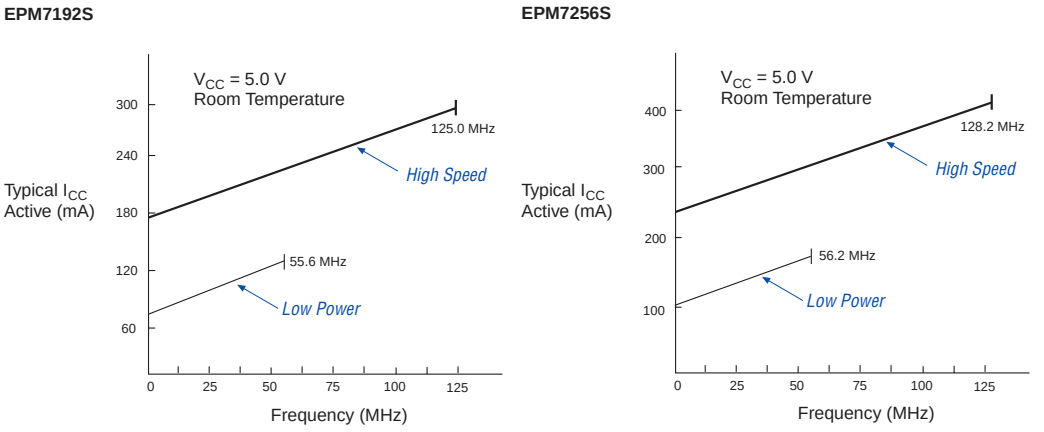
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		3.9		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t_{CH}	Global clock high time		3.0		4.0		5.0		ns
t_{CL}	Global clock low time		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		0.8		2.0		4.0		ns
t_{AH}	Array clock hold time		1.9		3.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			7.8		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	128.2		100.0		76.9		MHz
t_{ACNT}	Minimum array clock period			7.8		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	128.2		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		125.0		100.0		MHz

Table 39. MAX 7000 I_{CC} Equation Constants

Device	A	B	C
EPM7032	1.87	0.52	0.144
EPM7064	1.63	0.74	0.144
EPM7096	1.63	0.74	0.144
EPM7128E	1.17	0.54	0.096
EPM7160E	1.17	0.54	0.096
EPM7192E	1.17	0.54	0.096
EPM7256E	1.17	0.54	0.096
EPM7032S	0.93	0.40	0.040
EPM7064S	0.93	0.40	0.040
EPM7128S	0.93	0.40	0.040
EPM7160S	0.93	0.40	0.040
EPM7192S	0.93	0.40	0.040
EPM7256S	0.93	0.40	0.040

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)



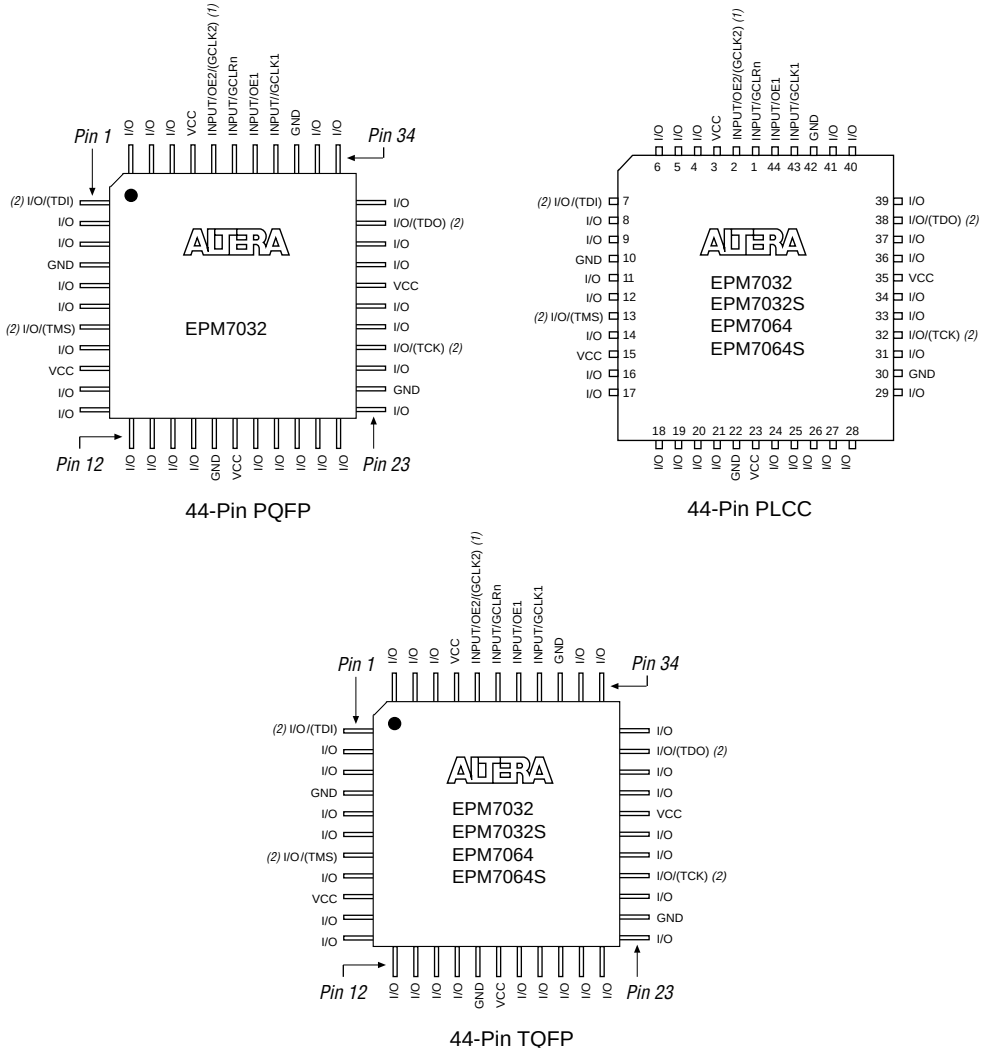
Device Pin-Outs

See the Altera web site (**http://www.altera.com**) or the *Altera Digital Library* for pin-out information.

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



44-Pin PQFP

44-Pin PLCC

44-Pin TQFP

Notes:
(1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
(2) JTAG ports are available in MAX 7000S devices only.

Notes:

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